

#### ■ Features

High Voltage Operation: VDS=50VHigh Power: 53.8dBm (typ.) @ Psat

· Proven Reliability

## Description

Sumitomo Electric's GaN-HEMT offers high efficiency, ease of matching, greater consistency and broad bandwidth for high power L-band amplifiers with 50V operation, and gives you higher gain. This new product is ideally suited for use from 1.8GHz to 2.0GH W-CDMA and LTE design requirements as it offers high gain, long term reliability and ease of use.



ABSOLUTE MAXIMUM RATINGS ( Case Temperature  $T_c = 25 \text{deg.C}$  )

Item	Symbol	Condition	Rating	Unit
Operating Voltage	$V_{DS}$		55	V
Drain-Source Voltage	$V_{DS}$	$V_{GS}$ =-8 $V$	160	V
Gate-Source Voltage	$V_{GS}$		-15	V
Total Power Dissipation	P <sub>t</sub>		160.7	W
Storage Temperature	T <sub>stg</sub>		-65 to +175	deg.C
Channel Temperature	Tch		250	dea.C

RECOMMENDED OPERATING CONDITION

Item	Symbol	Condition	Limit	Unit
DC Input Voltage	$V_{DS}$		<u>&lt;</u> 55	V
Forward Gate Current	${ m I}_{\sf GF}$	R <sub>G</sub> =5 ohm	<u>&lt;</u> 406	mA
Reverse Gate Current	$I_{GR}$	R <sub>G</sub> =5 ohm	<u>&gt;</u> -13.8	mA
Channel Temperature	$T_ch$		<u>&lt;</u> 200	deg.C
Average Output Power	P <sub>ave</sub> .		<u>&lt;</u> 51.0	dBm

ELECTRICAL CHARACTERISTICS ( Case Temperature  $T_c = 25 \text{deg.C}$  )

Item	Symbol	Condition	Condition Limit			Unit	
	Symbol	Condition	Min.	Typ.	Max.	Oiiit	
Pinch-Off Voltage	$V_p$	$V_{DS}$ =50V $I_{DS}$ =48mA	-4.0	=-	-2.0	V	
Saturated Power	Psat *1	$V_{DS}=50V$	53.2	53.8	-	dBm	
Drain Eficiency at Psat	DE *1	$I_{DS(DC)}$ =0mA f=1.88GHz	50.0	60.0	-	%	
Power Gain	Gp *2	$V_{DS}$ =50V $I_{DS(DC)}$ =800mA f=1.88GHz	15.5	16.5	-	dB	
Thermal Resistance	R <sub>th</sub>	Channel to Case at 105W P <sub>DC</sub>	-	1.2	1.4	deg.C/W	
Load Mismatch Ruggedness *3	-	VSWR 10:1		No f	ailures		

<sup>\*1:10%-</sup>duty RF pulse ( DC supply constant )

<sup>\*3 :</sup> Fixed Pin : Pout=P3dB at RL=50ohm, pulsed CW signal(10% duty)

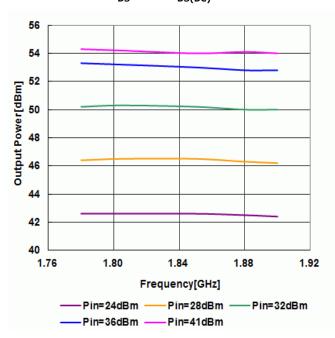
RoHS Compliance	YES

<sup>\*2 :</sup> Pout=46dBm, CW modulation Signal ( W-CDMA )

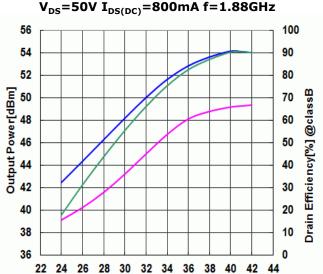


#### RF characteristics @ f=1.88GHz fine tuned

# Output Power vs. Frequency $V_{DS}$ =50V $I_{DS(DC)}$ =800mA



# Output Power and Drain Efficiency vs. Input Power

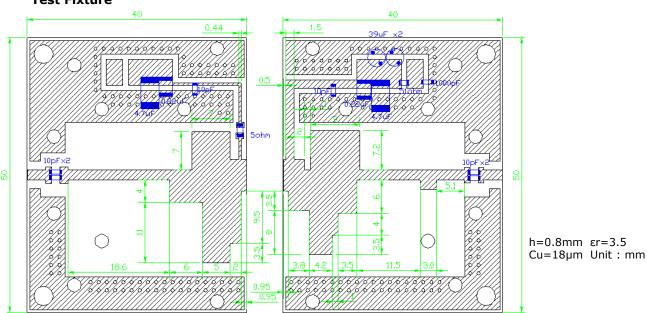


Pout Pout (class B) DE (class B)

Input Powr[dBm]

## Pulse Signal (10%-duty, DC: constant)

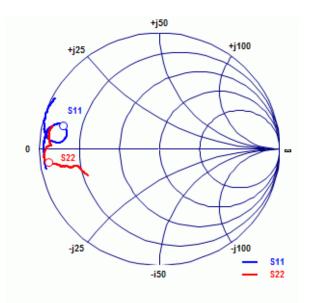
#### **Test Fixture**

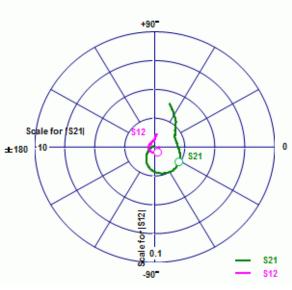




## - Reference DATA -

S-Parameters @VDS=50V, IDS(DC)=800mA, f=0.5 to 4.5GHz ZI = Zs = 50 ohm Marker : 1.84GHz

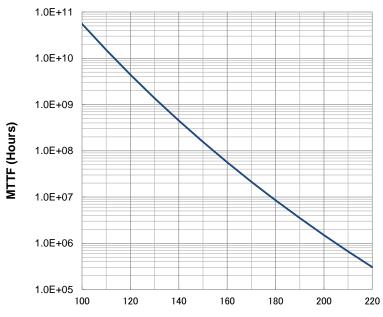




Freq.	5	11	s	21	5	12	s	22
GHz	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
0.5	0.96	-169.66	4.00	72.07	0.004	7.35	0.64	-159.28
0.6	0.97	-176.75	3.29	61.16	0.004	1.50	0.67	-163.45
0.7	0.97	176.66	2.80	50.41	0.004	-4.67	0.70	-167.99
0.8	0.96	175.44	2.45	45.52	0.004	-5.10	0.72	-168.23
0.9	0.96	174.43	2.24	41.00	0.004	-5.38	0.74	-168.15
1.0	0.96	173.59	2.10	35.76	0.004	-4.31	0.75	-168.02
1.1	0.96	172.65	1.97	30.92	0.004	-3.99	0.77	-168.45
1.2	0.96	171.63	1.87	25.83	0.004	-6.67	0.79	-169.36
1.3	0.95	170.18	1.85	19.92	0.004	-9.23	0.81	-169.37
1.4	0.94	169.34	1.87	13.57	0.004	-12.54	0.83	-169.67
1.5	0.94	168.31	1.90	7.37	0.004	-17.61	0.84	-170.22
1.6	0.91	167.17	1.97	-0.66	0.004	-23.50	0.86	-171.14
1.7	0.88	165.64	2.12	-11.45	0.004	-33.41	0.88	-171.59
1.8	0.85	165.45	2.35	-25.59	0.005	-52.68	0.91	-172.15
1.9	0.80	167.22	2.49	-44.42	0.005	-80.91	0.96	-173.74
2.0	0.78	171.28	2.46	-65.97	0.005	-116.10	0.97	-176.45
2.1	0.82	175.47	2.14	-90.12	0.005	-152.81	0.95	-179.43
2.2	0.87	176.04	1.70	-109.48	0.005	172.92	0.94	179.10
2.3	0.92	175.11	1.31	-122.84	0.005	148.83	0.93	178.32
2.4	0.94	173.93	1.02	-132.89	0.005	132.99	0.92	177.95
2.5	0.96	172.22	0.80	-140.53	0.005	120.98	0.91	177.89
2.6	0.97	170.95	0.64	-147.14	0.005	112.07	0.91	177.62
2.7	0.98	169.83	0.53	-152.17	0.005	106.65	0.91	177.25
2.8	0.98	168.65	0.45	-156.55	0.005	102.53	0.91	176.87
2.9	0.98	167.86	0.38	-160.95	0.005	99.08	0.91	176.61
3.0	0.99	166.90	0.33	-164.13	0.005	98.34	0.92	176.28
3.1	0.99	166.05	0.29	-167.23	0.006	94.50	0.92	175.59
3.2	0.99	165.13	0.26	-170.31	0.006	94.16	0.92	175.07
3.3	0.99	164.27	0.24	-173.64	0.006	92.20	0.93	174.77
3.4	1.00	163.39	0.22	-176.56	0.006	92.47	0.93	174.39
3.5	1.00	162.70	0.20	-179.22	0.007	91.23	0.93	173.59
3.6	1.00	161.61	0.19	177.83	0.007	90.84	0.93	172.72
3.7	0.99	160.82	0.18	174.07	0.007	88.08	0.93	172.47
3.8	0.99	159.83	0.17	170.69	0.008	88.05	0.93	171.75
3.9	1.00	158.81	0.17	167.38	0.008	87.81	0.93	171.09
4.0	0.99	157.91	0.16	163.88	0.009	85.34	0.93	170.37
4.1	0.99	157.31	0.16	160.34	0.009	85.23	0.93	169.93
4.2	0.99	156.30	0.16	156.83	0.009	84.21	0.93	169.54
4.3	0.99	155.07	0.16	152.74	0.010	84.43	0.93	168.62
4.4	0.98	154.14	0.16	148.53	0.011	84.02	0.92	168.12
4.5	0.98	153.32	0.17	144.44	0.011	81.51	0.92	167.60



MTTF Calculation
- Estimated MTTF -



**Channel Temperature (deg. C)** 

Ea=1.6eV Confidence Level=90%

Channel Temp (deg.C)	MTTF (Hours)
160	5.98 x 10 <sup>7</sup>
180	$9.02 \times 10^6$
200	1.60 x 10 <sup>6</sup>

 $AF=exp[(-Ea/k)(1/T_{stress}-1/T_{use})]$ 

MTTF<sub>use</sub>=MTTF<sub>stress</sub>\*AF

Where:

AF: acceleration factor

Ea: activation energy (1.6 eV)

k: Boltzman's constant (8.62 x 10<sup>-5</sup> eV/K)

 $T_{\text{stress}}$ : stress temperature (K)  $T_{\text{use}}$ : use temperature (K)

#### **ESD** characteristic

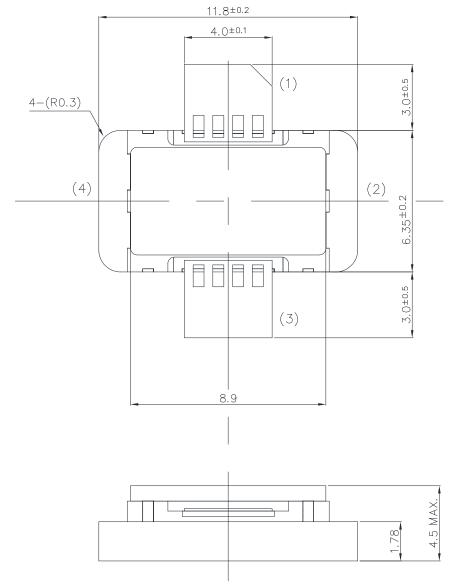
Test Methodology	Class
Human Body Model (per JESD22-A114)	1B
Machine Model (per JEIA/ESD22-A115)	А
Device Charged Model (per JESD22-C101)	IV

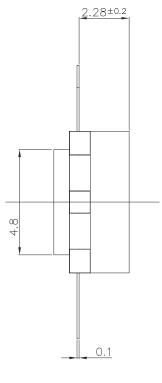
## **Ordering Information**

Part Number	MOQ / MOU	Tray Style
SGN19H240M1H	No Limitation	30pcs Tray ( 30 pockets )
SGN19H240M1H/001	No Limitation	JEDEC Tray ( 100 pockets )



### M1H Package Outline Metal-Ceramic Hermetic Package





- 1. Gate
- 2. Source
- 3. Drain
- 4. Source

Unit: mm

Talerance:  $\pm 0.15$ 



### For Safety, Observe the Following Procedures Environmental Management

- Do not put this product into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Respect all applicable laws of the country when discarding this product.
   This product must be disposed in accordance with methods specified by applicable hazardous waste procedures.

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